



100% Material Declaration Data Sheet for 7 Series CLG225 Package

PK612 (v1.0) July 5, 2013

Average Weight: 0.4710 g

Component	Substance Description	CAS# or Description	% of Component	Use in Product	Component Weight/ Substance Weight (in grams)	Component % of Total
Silicon Die					0.014830	3.149%
	Silicon	7440-21-3	100.00		0.014830	
Die Attach					0.003759	0.798%
	Silver	7440-22-4	77.50		0.002913	
	Bismaleimide monomer	Trade Secret	15.00		0.000564	
	Acrylate monomer	Trade Secret	7.50		0.000282	
Mold Compound					0.220830	46.885%
	Epoxy Resin	Trade Secret	5.00		0.011042	
	Phenol Resin	Trade Secret	3.00		0.006625	
	Phenol Novolac	9003-35-4	3.00		0.006625	
	Metal Hydroxide	Trade Secret	3.00		0.006625	
	Carbon Black	1333-86-0	0.30		0.000662	
	Silica fused	60676-86-0	70.40		0.155464	
	Silica fused	7631-86-9	15.00		0.033125	
	Silica, crystalline	14808-60-7	0.30		0.000662	
Copper Wire					0.003519	0.747%
	Copper	7440-50-8	98.25		0.003457	
	Palladium	7440-05-3	1.75		0.000062	
Solder Balls					0.055691	11.824%
	Tin	7440-31-5	96.50		0.053742	
	Silver	7440-22-4	3.00		0.001671	
	Copper	7440-50-8	0.50		0.000278	
Substrate					0.172371	36.597%
	Copper	7440-50-8	45.65		0.078681	
	Nickel	7440-02-0	1.78		0.003075	
	Gold	7440-57-5	0.30		0.000524	
	Glass Fiber	65997-17-3	20.46		0.035268	
	BT Core	Trade Secret	25.01		0.043106	
	Solder Mask	Trade Secret	6.80		0.011717	

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Revision History

The following table shows the revision history for this document.

Date	Version	Description of Revisions
07/05/13	1.0	Initial Xilinx release.

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